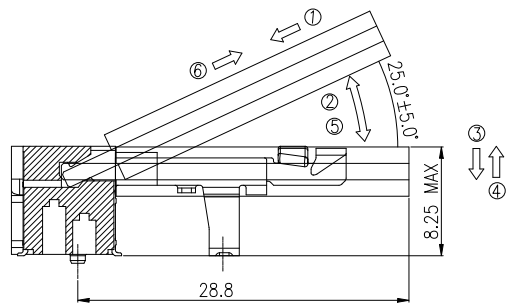
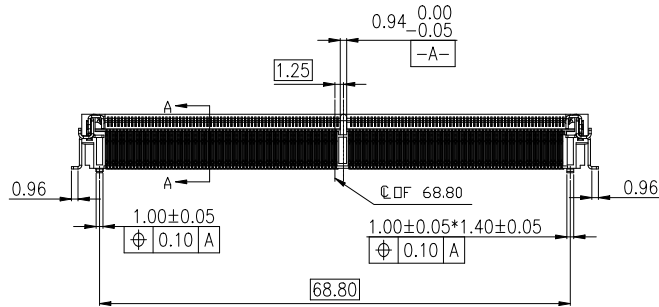
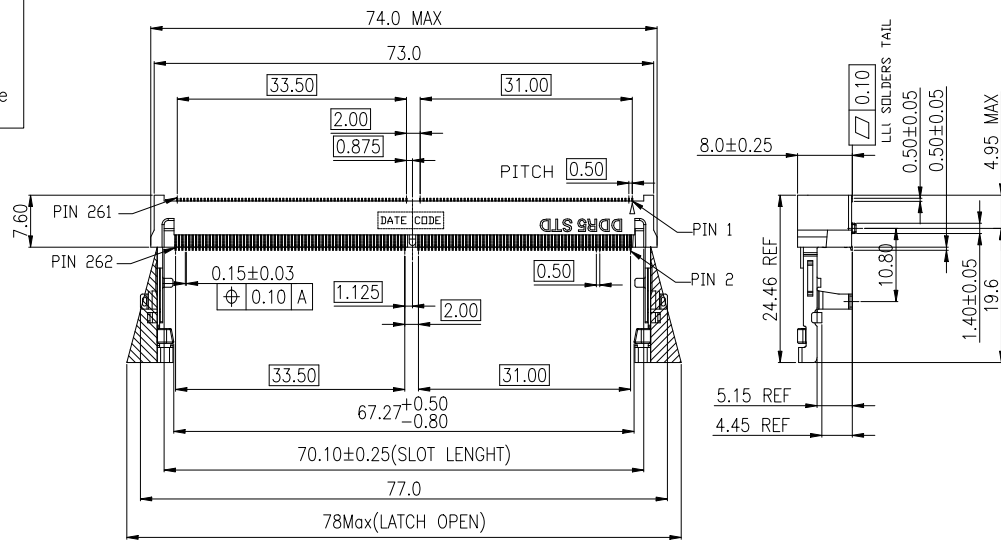
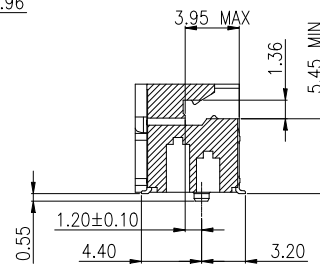
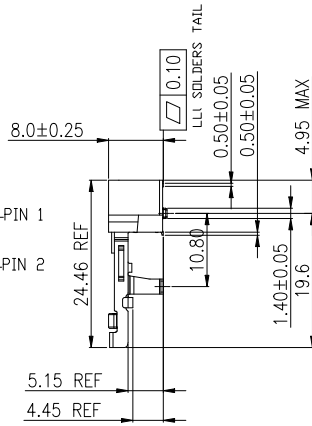


HF

Halogen Free



MATING: ① INSERTING(20°~30°) → ② ROTATING → ③ FIXED
 UNMATING: ④ UNFIXED → ⑤ ROTATING → ⑥ WITHDRAWING



REV.	ECN NO.	LOCATION	DESCRIPTION	DATE	DESIGN
A			INITIAL RELEASE	08/01'23	HC

- NOTES:
 PRODUCT MUST MEET CONTROLLED SUBSTANCES SPEC.DEREN PER WI-PB-S-010
- MATERIAL:
 - HOUSING:LCP,UL94V-0,COLOR:BLACK.
 - CONTACT:PHOSPHOR BRONZE.
 - LATCH:STAINLESS STEEL.
 - FINISH:
 - CONTACT:
 - 50u" MIN NICKEL UNDERPLATED ALL OVER.
 - GOLD FLASH PLATING ON SOLDER TAIL.
 - GOLD PLATING (THICKNESS SEE P/N) ON CONTACT AREA.
 - SOLDER PEG:
 - 50u" MIN NICKEL UNDERPLATED ALL OVER.
 - 100u" MIN MATTE TIN PLATING ENTIRE OVER.
 - ELECTRICAL CHARACTERISTICS:
 - CONTACT CURRENT RATING: 0.5 AMPERE MAX. PER PIN.
 - VOLTAGE RATING: 1.2V DC.
 - INSULATION RESISTANCE: 100 MEGAOHMS MIN. AT 500V DC.
 - DIELECTRIC WITHSTANDING VOLTAGE: 250V AC RMS AT 60HZ, FOR 1 MINUTE.
 - CONTACT RESISTANCE: 40 MILLIOHMS MAX. PER PIN INITIAL
20 MILLIOHMS PER PIN AFTER FULL ENVIRONMENTAL TESTING.
 - MECHANICAL CHARACTERISTICS: DURABILITY: 25CYCLES
 - OPERATION TEMPERATURE: -55 C TO +85
 - RECOMMENDED PROCESS CONDITION: SMT, PEAK TEMPERATURE: 260c 20~40S.
 - PLEASE CONTACT FOXCONN SALES REPRESENTATIVE TO VERIFY PRODUCT DETAILS & AVAILABILITY.
 - MSL LEVEL: MSL(MOISTURE SENSITIVITY LEVEL)=1
 - DATE CODE: YYWDXLX
 - YY: YEAR (09: 2009)
 - WW: WEEK (25: THE 25TH WEEK)
 - D: DAY (1~7: SUNDAY~SATURDAY)
 - L: LINE NUMBER OF ASSEMBLY (A: LINE A)
 - X: MANUFACTURE CODE
 - RECOMMENDED STENCIL THICKNESS: 0.12mm Min.
 - PART NUMBER DESCRIPTION:

567YD2-003H X S 3 X R

PACKING CODE:
 R: TAPE & REEL
 LOGO:
 0: NO LOGO
 1: DR LOGO
 RESERVED
 KEY TYPE:
 S: STD

PLATING CODE: 1: GF 2: Au5u"
 3: Au10u" 4: Au15u"
 5: Au30u"

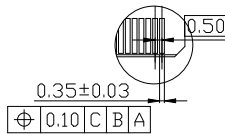
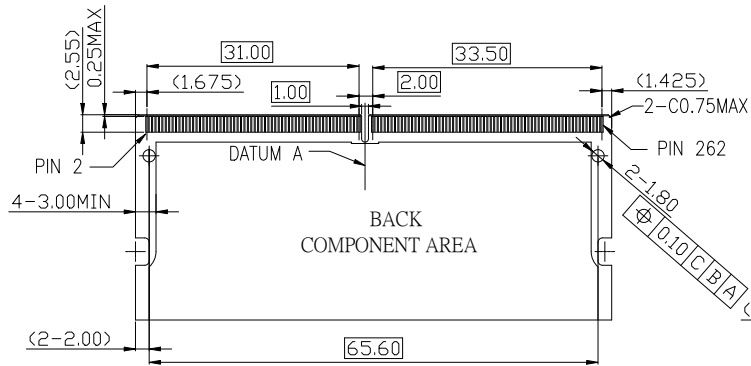
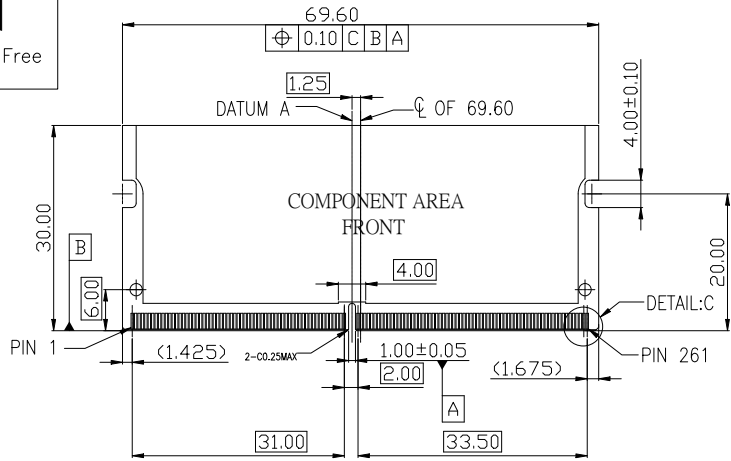
HALOGEN CODE:
 H: HALOGEN FREE

DIM	TOL	DIM	TOL	DEREN SHENZHEN DEREN ELECTRONIC CO., LTD			
X.	±0.30	X.	±2'	C-DWG:	TY	DATE	TITLE: DDR5 SO DIMM 262PIN 8.OH STD METAL LATCH C-DWG
.X	±0.25	.X	±1'	DRAW NO.	DESIGN:	HC	2024.08.01
.XX	±0.20			SC2006359-17	CHECK:	Chen.ZF	2024.08.01
				REV. A	APPROVAL:	Bill.Lin	2024.08.01
							SHEET: 1/3
							SCALE: N/A UNIT: mm

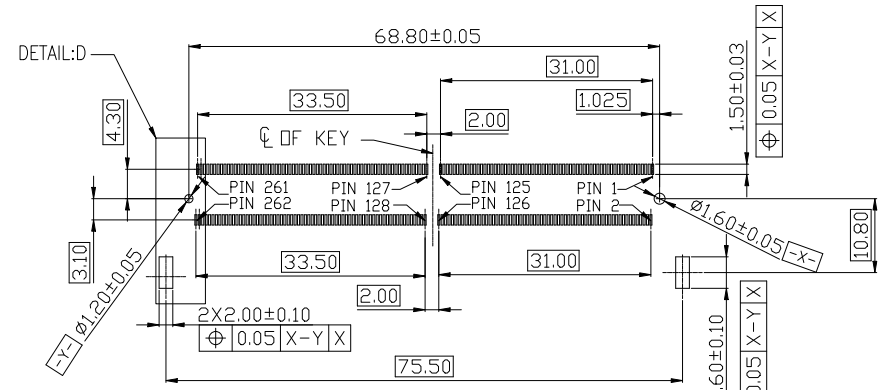
HF

Halogen Free

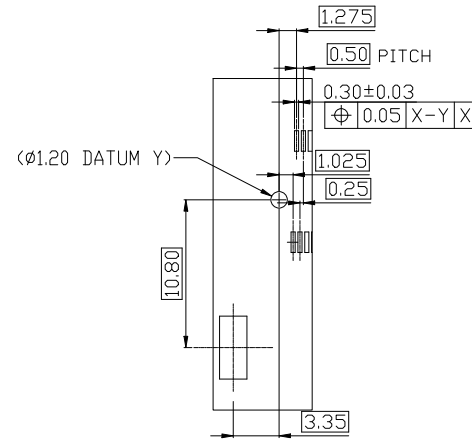
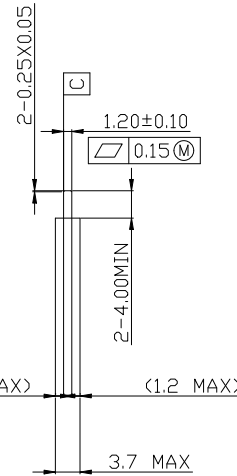
REV.	ECN NO.	LOCATION	DESCRIPTION	DATE	DESIGN
A			INITIAL RELEASE	08/01'23	HC



DETAIL:C
SCALE 2:1



RECOMMEND PCB LAYOUT(TOP VIEW)
THE TOLERANCE UNLESS SPECIFIED IS ±0.05MM



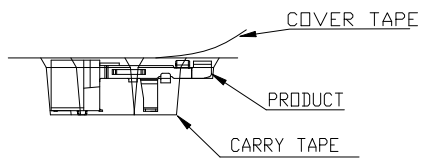
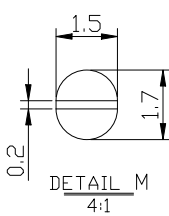
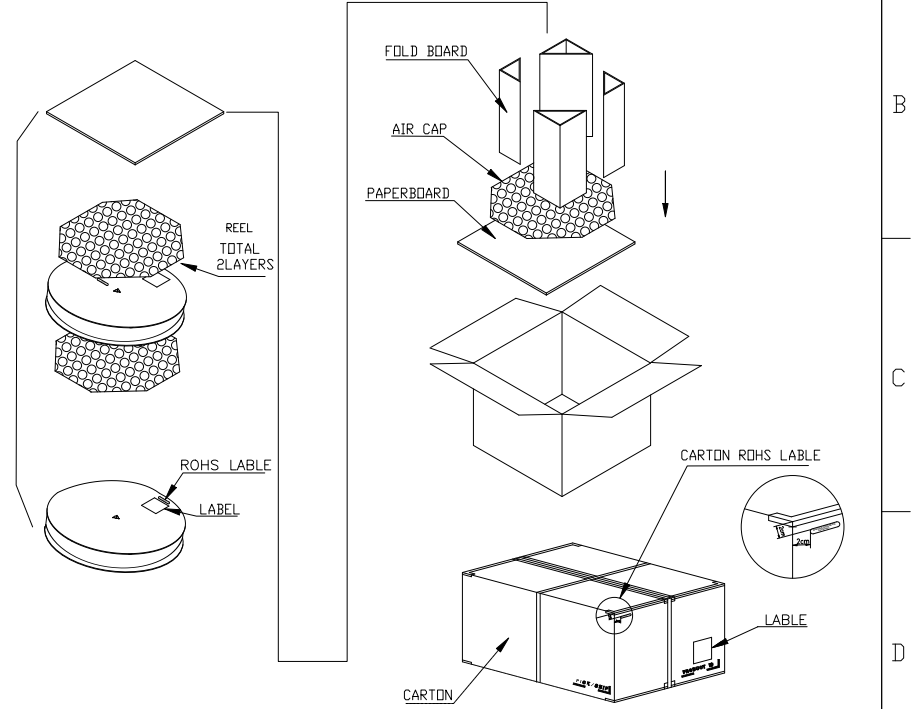
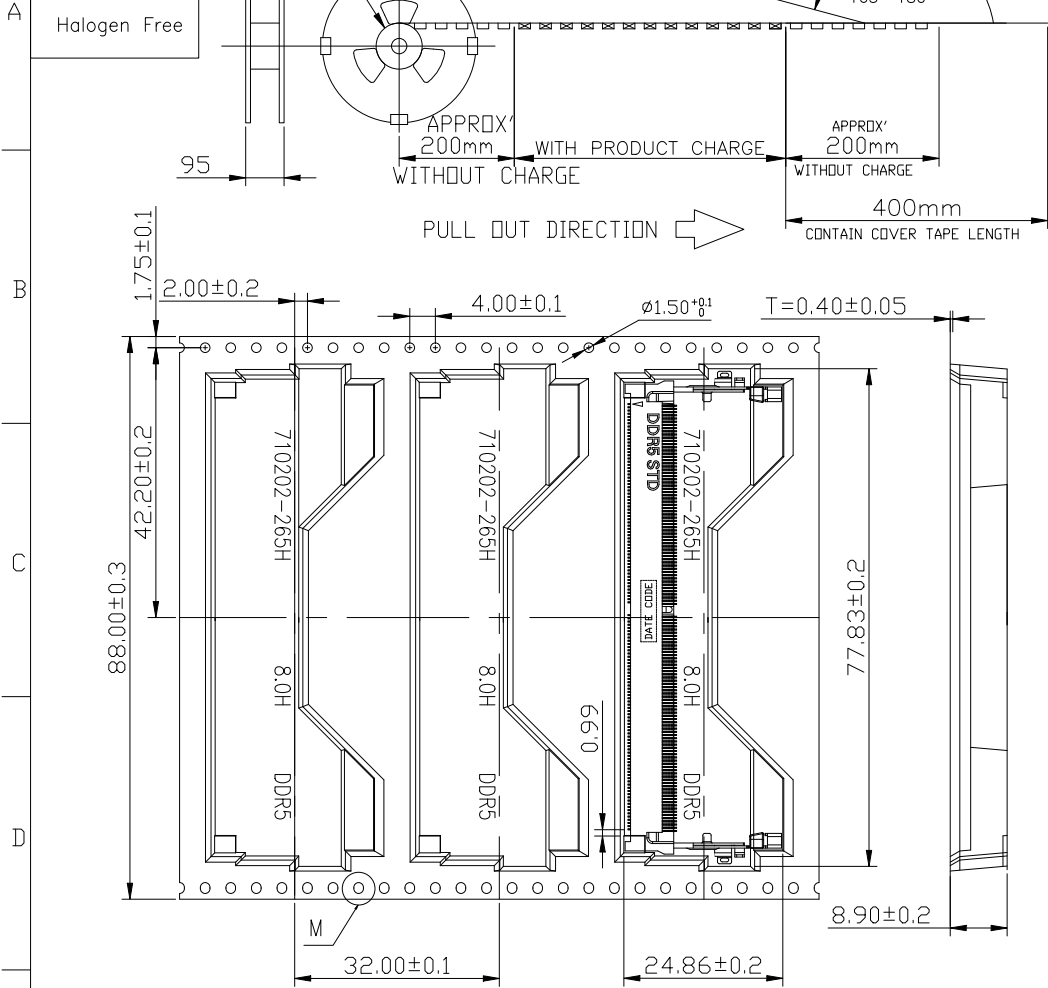
DETAIL:D
SCALE 2:1

DIM	TOL	DIM	TOL	DEREN SHENZHEN DEREN ELECTRONIC CO., LTD			
X.	±0.30	X.	±2'	DRAW NO. SC2006359-17	DESIGN: HC	DATE 2024.08.01	TITLE: DDR5 SO DIMM 262PIN 8.OH STD METAL LATCH C-DWG
.X	±0.25	.X	±1'				
.XX	±0.20			REV. A	CHECK: Chen.ZF	DATE 2024.08.01	P/N: 567YD2-003HXS3XR
				APPROVAL: Bill.Lin	DATE 2024.08.01	SHEET: 2/3	SCALE: N/A
						UNIT: mm	

HF

Halogen Free

REV.	ECN NO.	LOCATION	DESCRIPTION	DATE	DESIGN
A			INITIAL RELEASE	08/01'23	HC



250	2	500	SEE P/N
PCS/ REEL	REEL/ CARTON	PCS/ CARTON	PART NUMBER

DIM	TOL	DIM	TOL	DEREN SHENZHEN DEREN ELECTRONIC CO., LTD				
X.	±0.30	X.	±2'	DRAW NO. SC2006359-17	C-DWG:	TY	DATE	TITLE: DDR5 SO DIMM 262PIN 8.0H STD METAL LATCH C-DWG
.X	±0.25	.X	±1'		DESIGN:	HC	2024.08.01	P/N: 567YD2-003HXS3XR
.XX	±0.20				CHECK:	Chen.ZF	2024.08.01	SHEET: 3/3
				REV.	A	APPROVAL:	Bill.Lin	2024.08.01
								SCALE: N/A UNIT: mm